

IN THE CLAIMS

1. (currently amended) A composition for etching a polymer substrate comprising a dihydric alcohol having from two to five carbon atoms, a hydroxide compound selected from the group consisting of lithium hydroxide, sodium hydroxide, potassium hydroxide, calcium hydroxide, barium hydroxide, strontium hydroxide and mixtures thereof, and water, wherein said dihydric alcohol and said water are present in a ratio of from about 0.5:1 to about 8.5:1.

2. (original) The composition of Claim 1, wherein said dihydric alcohol comprises glycol and said hydroxide comprises potassium hydroxide.

3. (original) The composition of claim 1, further including an inhibitor selected from the group consisting of NaF, CH₃COONa, CH₃COOK, K₂CO₃, Na₂CO₃, K₃PO₄, hexamethylene tetramine, and mixtures thereof.

4. (cancelled)

5. (currently amended) The composition of claim 4₁, wherein said hydroxide compound is present in an amount of from about 40 to about 80 grams per 100 ml of dihydric alcohol and water solution.

6. (original) The composition of claim 1, wherein said hydroxide compound is present in an amount of from about 40 to about 80 grams per 100 ml of dihydric alcohol and water solution.

7. (original) The composition of claim 1, wherein said water comprises deionized water.

8. (currently amended) A composition for etching an opening in a polymer substrate comprising glycol, potassium hydroxide and deionized water, wherein said glycol and said water are present in a ratio of from about 0.5:1 to about 8.5:1 and said potassium hydroxide is present in an amount of from

about 40 to about 80 grams per 100 ml of glycol and water solution.

9. (original) The composition of claim 8, further including an inhibitor selected from the group consisting of NaF, CH_3COONa , CH_3COOK , K_2CO_3 , Na_2CO_3 , K_3PO_4 , hexamethylene tetramine, and mixtures thereof.

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31. (original) The composition of claim 1, wherein said composition has a boiling point in the range of from about 240°F to about 300°F.

32. (original) The composition of claim 1, wherein said composition has a boiling point in the range of from about 260°F to about 280°F.

33. (original) The composition of claim 8, wherein said composition has a boiling point in the range of from about 240°F to about 300°F.

34. (original) The composition of claim 8, wherein said composition has a boiling point in the range of from about 260°F to about 280°F.

35. (original) The composition of claim 1, wherein said substrate comprises a polyimide substrate.

36. (original) The composition of claim 8, wherein said substrate comprises a polyimide substrate.

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